Vishay Siliconix



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Dual N-Channel 60 V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	R _{DS(on)} (Ω) MAX.	I _D (A)	Q _g (nC) TYP.			
60	1.4 at V _{GS} = 10 V	0.37	0.47			
	3 at V _{GS} = 4.5 V	0.25	0.47			

SOT-363 SC-70 Dual (6 leads)



Marking Code: PD Ordering Information:

Si1926DL-T1-E3 (Lead (Pb)-free)

Si1926DL-T1-GE3 (Lead (Pb)-free and Halogen-free)

FEATURES

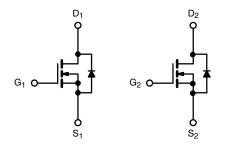
- TrenchFET® power MOSFET
- 100 % R_g tested
- ESD protected: 1800 V
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912





APPLICATIONS

· Low power load switch



N-Channel MOSFET

N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		V _{DS}	60	V	
Gate-Source Voltage		V _{GS}	± 20	V	
	T _C = 25 °C		0.37		
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 70 °C	,	0.30		
Continuous Drain Current (1) = 150 C)	T _A = 25 °C	l _D	0.34 ^{b, c}	A	
	T _A = 70 °C		0.27 ^{b, c}		
Pulsed Drain Current		I _{DM}	0.65	1	
Continuous Source-Drain Diode Current	T _C = 25 °C		0.43		
Continuous Source-Drain Diode Current	T _A = 25 °C	- I _S	0.25 ^{b, c}		
	T _C = 25 °C		0.51		
Maximum Bower Dissination	T _C = 70 °C	Б.	0.33	W	
Maximum Power Dissipation	T _A = 25 °C	P _D	0.30 ^{b, c}	T vv	
	T _A = 70 °C	1	0.20 b, c	1	
Operating Junction and Storage Temperature R	T _J , T _{stg}	-55 to +150	°C		

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT	
Maximum Junction-to-Ambient b, d	t ≤ 5 s	R _{thJA}	360	415	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	300	350	C/VV	

Notes

- a. Based on $T_C = 25$ °C.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 5 s.
- d. Maximum under steady state conditions is 400 $^{\circ}\text{C/W}.$

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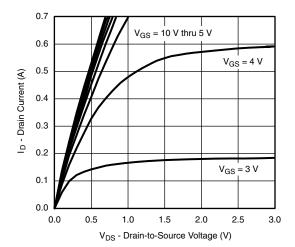
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT		
Static							
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	60	-	-	V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J 050 A	-	56.7	-	mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	$I_D = 250 \mu A$	-	-3	-		
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1	-	2.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 10 \text{ V}$	-	-	± 150	nA	
Zana Oata Waltana Duain Ourona		V _{DS} = 60 V, V _{GS} = 0 V	-	-	1	μА	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 60 V, V _{GS} = 0 V, T _J = 85 °C	-	-	10		
Ox Olale Burio Ox and I		$V_{DS} \ge 10 \text{ V}, V_{GS} = 4.5 \text{ V}$	0.50	-	-	- A	
On-State Drain Current ^a	I _{D(on)}	V _{DS} ≥ 7.5 V, V _{GS} = 10 V	0.65	-	-		
Duit On the Ordina Projection of	1	$V_{GS} = 10 \text{ V}, I_D = 0.34 \text{ A}$	-	-	1.4	Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 0.23 \text{ A}$	-	-	3		
Forward Transconductance	9 _{fs}	$V_{DS} = 30 \text{ V}, I_D = 0.2 \text{ A}$	-	159	-	ms	
Dynamic ^b			l .	1	•	•	
Input Capacitance	C _{iss}		-	18.5	-	pF	
Output Capacitance	C _{oss}	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	7.5	-		
Reverse Transfer Capacitance	C _{rss}		-	4.2	-		
T 0 0.	Q _g	V _{DS} = 30 V, V _{GS} = 10 V, I _D = 0.34 A	-	0.9	1.4	nC	
Total Gate Charge			-	0.5	0.75		
Gate-Source Charge	Q _{gs}	$V_{DS} = 30 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 0.34 \text{ A}$	-	0.2	-		
Gate-Drain Charge	Q_{gd}		-	0.15	-		
Gate Resistance	R_g	f = 1 MHz	-	160	240	Ω	
Turn-On Delay Time	t _{d(on)}		-	6.5	10		
Rise Time	t _r	$V_{DD} = 30 \text{ V}, R_{L} = 100 \Omega,$	-	12	18	- ns	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 0.3 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$	-	13	22		
Fall Time	t _f		-	14	21		
Drain-Source Body Diode Characteris	tics						
Continuous Sorce-Drain Diode Current	Is	T _C = 25 °C	-	-	0.43	1	
Pulse Diode Forward Current ^a	I _{SM}		-	-	0.65	A	
Body Diode Voltage	V _{SD}	I _S = 0.3 A	-	0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}		-	16.5	25	ns	
Body Diode Reverse Recovery Charge	ode Reverse Recovery Charge Q _{rr}		-	13	20	nC	
Reverse Recovery Fall Time	ta	I _F = 0.6 A, dI/dt = 100 A/μs	-	13.5	-		
everse Recovery Rise Time t _b		-	3	-	ns		

Notes

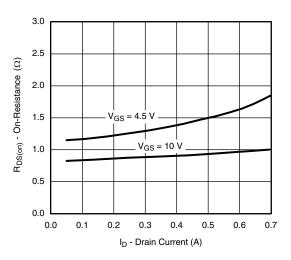
- a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

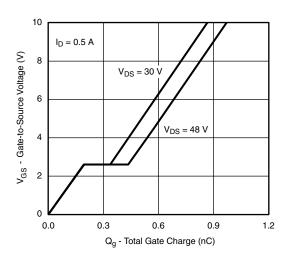




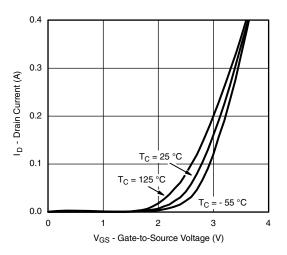
Output Characteristics



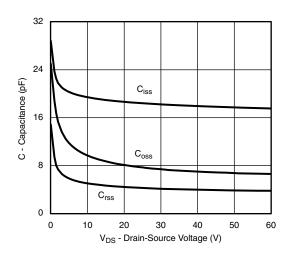
On-Resistance vs. Drain Current



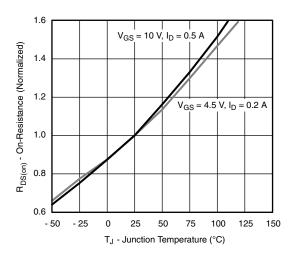
Gate Charge



Transfer Characteristics Curves vs. Temperature

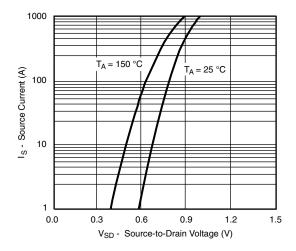


Capacitance

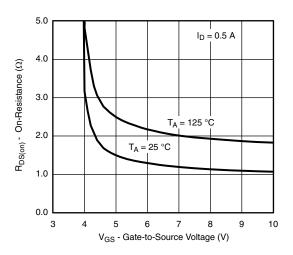


On-Resistance vs. Junction Temperature

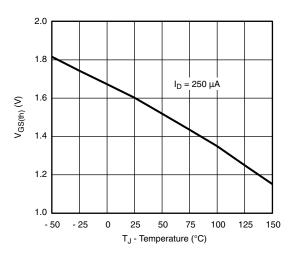




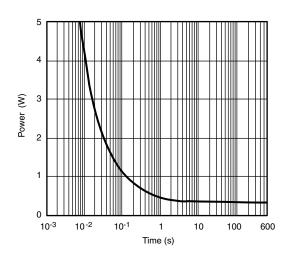
Source-Drain Diode Forward Voltage



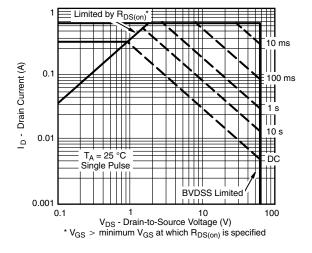
R_{DS(on)} vs. V_{GS} vs. Temperature



Threshold Voltage

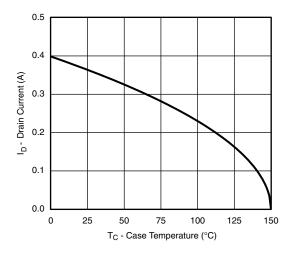


Single Pulse Power

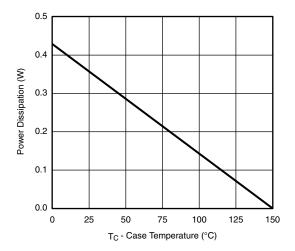


Safe Operating Area







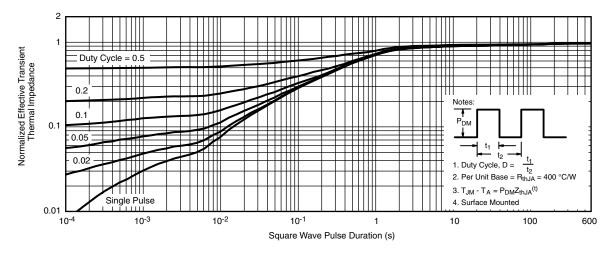


Power Derating

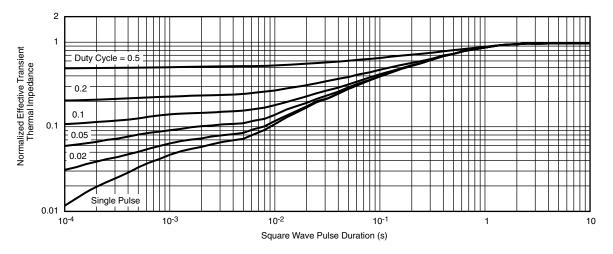
Note

a. The power dissipation P_D is based on T_{J (max.)} = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





Normalized Thermal Transient Impedance, Junction-to-Ambient

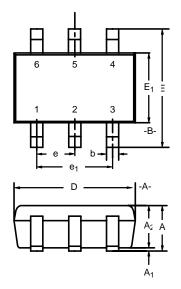


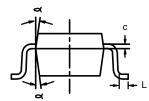
Normalized Thermal Transient Impedance, Junction-to-Foot

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?73684.



SC-70: 6-LEADS





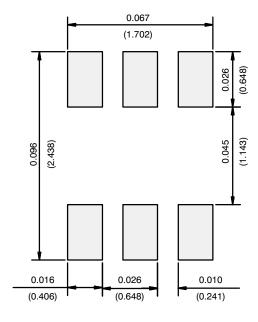
	MILLIMETERS			INCHES		
Dim	Min	Nom	Max	Min	Nom	Max
Α	0.90	-	1.10	0.035	-	0.043
A ₁	_	-	0.10	_	_	0.004
A ₂	0.80	-	1.00	0.031	_	0.039
b	0.15	-	0.30	0.006	_	0.012
С	0.10	-	0.25	0.004	-	0.010
D	1.80	2.00	2.20	0.071	0.079	0.087
Е	1.80	2.10	2.40	0.071	0.083	0.094
E ₁	1.15	1.25	1.35	0.045	0.049	0.053
е	0.65BSC				0.026BSC	;
e ₁	1.20	1.30	1.40	0.047	0.051	0.055
L	0.10	0.20	0.30	0.004	0.008	0.012
۵	7°Nom			7°Nom		
ECN: S-03946—Rev. B, 09-Jul-01						

DWG: 5550

Document Number: 71154 www.vishay.com 06-Jul-01 sww.vishay.com



RECOMMENDED MINIMUM PADS FOR SC-70: 6-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOT





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